

AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions, and listings, of claims in the application.

Listing of Claims:

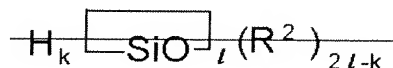
1. (Currently Amended) Organic siloxane resins for insulation films having a dielectric constant in the range of 2.24 to 2.48 and a mechanical strength in the range of 6 to 8 GPa, which are condensed polymers, manufactured by a hydrolysis and condensation reaction of silane compounds ~~consisting essentially of one or more kinds of hydrosilane compounds in the presence of a base catalyst, wherein the only~~ hydrosilane compounds, wherein at least one hydrosilane compound ~~[[have]]~~ has the following Chemical Formula 1, ~~or are oligomers manufactured from the silane compounds in the Chemical Formula 1 or cyclic siloxane compounds having the following Chemical Formula 2, and the weight average molecular weight of the resins is at least 5,000;~~

[Chemical Formula 1]



wherein R¹ is independently fluorine, aryl, vinyl, allyl, or linear or branched alkyl having 1 to 4 carbon atoms, or alkoxy; and n is an integer of 1 to 3; ~~and~~

~~[Chemical Formula 2]~~



~~wherein R² is independently fluorine, aryl, vinyl, allyl, or linear or branched alkyl having 1 to 4 carbon atoms, or alkoxy; and k and l are integers of 3 to 10.~~

2-4. (Canceled)

5. (Currently Amended) Compositions for forming insulating films comprising said organic siloxane resins having a dielectric constant in the range of 2.24 to 2.48 and a mechanical strength in the range of 6 to 8 GPa, manufactured according to Claim 1.

6. (Currently Amended) A method of forming insulating films using organic siloxane resins comprising the steps of:

- a) preparing an organic siloxane resin according to claim 1;
- b) dissolving the organic siloxane resin in an organic solvent to prepare a solution;
- c) forming an insulating film by coating the solution; and
- d) drying and hardening the insulating film formed in the step c) to prepare insulation films having dielectric constant in the range of 2.24 to 2.48 and mechanical strength in the range of 6 to 8 GPa.

7. (Previously Presented) The method of forming a insulating film using said organic siloxane resins according to Claim 6, further comprising a step, after the above step b), of adding one or more kinds of additives selected from the group consisting of organic molecules, water, pH controlling agents, colloidal silica, and surfactants to said solution.

8. (Previously Presented) Insulation films using organic siloxane resins manufactured by drying and hardening insulating films formed by coating the solution, which is prepared by dissolving said organic siloxane resins according to Claim 1 in an organic solvent, onto a substrate.

9. (Previous Presented) Electronic devices comprising insulating films using organic siloxane resins manufactured by drying and hardening of insulating films formed by coating the solution, which is prepared by dissolving said organic siloxane resins according to Claim 1 in an organic solvent, onto a substrate.